

Product Overview

Materials



Vacuum Printing Encapsulation
Material/System



Bonding Wire (Au, Cu)
Solder Balls



Die / Wire Bonding Tools,
Capillaries, Accessories



Mold Compound (green, clear etc.)



Memory Module Test Sockets
Burn-In/Test Sockets (BGA, QFN etc.)

Mold Cleaning Material (Sheets/Pellets)
Dicing Blades

High Temperature Range Probe Card
High Frequency Probe Card
High Pin Count Probe Card



Equipment

Molding Equipment
Trim&Form Equipment
Singulation Equipment
Laser Marking/Ablation Equipment
Pick&Place Equipment
Flip Chip Bonder

Pressure Oven for Void Free Solution

Wafer Bonding Systems

Direct Plasma Cleaning Systems
Batch Plasma Cleaning Systems

WLP Wafer Level Solderball Mounter
CSP Solderball Mounter
Laser Heater Flip Chip Bonder

Conduction/Convection Reflow Systems

Burn-In Board Loading/Unloading Systems
Component Test Handling Systems

Memory Module Test Handling Systems
Memory Testing Systems
LED Prober & Sorter
LED Die Bonder